



Advanced Micro/Nano Device and System Technology

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Message from the Guest Editor

Dear Colleagues,

Micro-nano technology-based advanced Micro/Nano Device and System have become the future development direction due to their remarkable characteristics of miniaturization, intelligence, high integration and high density. It involves a variety of technologies such as device design, micro-nano film deposition and patterned, wafer bonding, silicon interconnection, three-dimensional intergration, system packaging and device characterization technology. The newly emerging nano-technological advancements, such as quantum effects, interface effects and nanoscale effects, have provided new impetus for the next generation of micro and nano devices and systems.

This special issue is dedicated to organizing and summarizing the current research status of advanced micro-nano devices and systems and sharing the latest progresses in the field of advanced micro-nano device and system research. Original research achievements and review literature from the fields of Working principles, new design concepts, MEMS fabrication technology, system integration method, on-chip control technology, etc., related to micro-nano devices and technology are all welcomed.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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